



3N90

Power MOSFET

3A, 900V N-CHANNEL POWER MOSFET

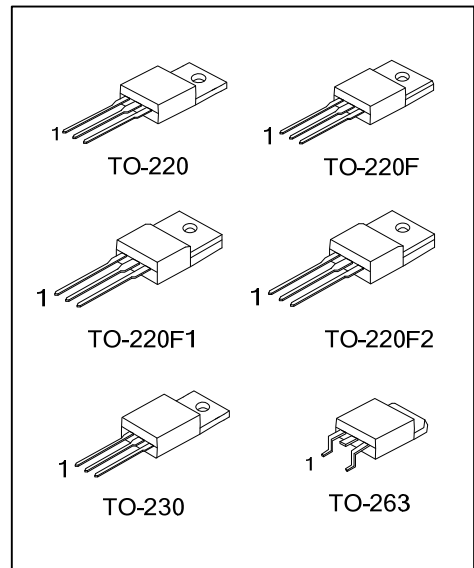
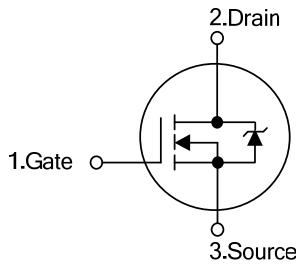
■ DESCRIPTION

The UTC **3N90** provides excellent $R_{DS(ON)}$, low gate charge and operation with low gate voltages. This device is suitable for use as a load switch or in PWM applications.

■ FEATURES

- * $R_{DS(ON)} < 4.8 \Omega @ V_{GS} = 10 V$
- * Fast Switching Capability
- * Avalanche Energy Specified
- * Improved dv/dt Capability, High Ruggedness

■ SYMBOL



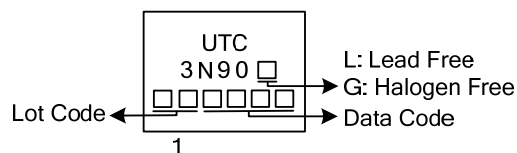
■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
3N90L-TA3-T	3N90G-TA3-T	TO-220	G	D	S	Tube
3N90L-TC3-T	3N90G-TC3-T	TO-230	G	D	S	Tube
3N90L-TF3-T	3N90G-TF3-T	TO-220F	G	D	S	Tube
3N90L-TF1-T	3N90G-TF1-T	TO-220F1	G	D	S	Tube
3N90L-TF2-T	3N90G-TF2-T	TO-220F2	G	D	S	Tube
3N90L-TQ2-T	3N90G-TQ2-T	TO-263	G	D	S	Tube
3N90L-TQ2-R	3N90G-TQ2-R	TO-263	G	D	S	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source

	<p>(1) T: Tube, R: Tape Reel (2) TA3: TO-220, TC3: TO-230, TF3: TO-220F, TF1: TO-220F1, TF2: TO-220F2, TQ2: TO-263 (3) L: Lead Free, G: Halogen Free and Lead Free</p>
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■ MARKING



■ ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage ($V_{GS}=0V$)		V_{DSS}	900	V
Drain-Gate Voltage ($R_G=20k\Omega$)		V_{DGR}	900	V
Gate-Source Voltage		V_{GSS}	± 30	V
Gate-Source Breakdown Voltage ($I_{GS}=\pm 1mA$)		BV_{GSO}	30(MIN)	V
Continuous Drain Current		I_D	3	A
Pulsed Drain Current		I_{DM}	10	A
Single Pulse Avalanche Energy (Note 3)		E_{AS}	180	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.5	V/ns
Power Dissipation	TO-220/TO-263	P_D	90	W
	TO-230			
	TO-220F/TO-220F1		25	
	TO-220F2		26	
Junction Temperature		T_J	+150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 ~ +150	$^\circ\text{C}$

Note: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Pulse width limited by $T_{J(MAX)}$

3. $L = 40mH$, $I_{AS} = 3A$, $V_{DD} = 50V$, $R_G = 25 \Omega$, Starting $T_J = 25^\circ\text{C}$

4. $I_{SD} \leq 3A$, $di/dt \leq 200A/\mu s$, $V_{DD} \leq BV_{DSS}$, $T_J \leq T_{J(MAX)}$.

■ THERMAL DATA

PARAMETER		SYMBOL	RATING	UNIT
Junction to Ambient		θ_{JA}	62.5	$^\circ\text{C/W}$
Junction to Case	TO-220/ TO-263	θ_{JC}	1.38	$^\circ\text{C/W}$
	TO-230			
	TO-220F/TO-220F1		5	
	TO-220F2		4.9	

■ ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	900			V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=900V, V_{GS}=0V$			1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 30V, V_{DS}=0V$			± 10	μA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	3	3.75	4.5	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=1.5A$		4.1	4.8	Ω
Forward Transconductance (Note 1)	g_{FS}	$V_{DS}=15V, I_D=1.5A$		2.1		S
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{ISS}	$V_{DS}=25V, V_{GS}=0V, f=1\text{MHz}$		560		pF
Output Capacitance	C_{OSS}			69		pF
Reverse Transfer Capacitance	C_{RSS}			11		pF
Equivalent Output Capacitance (Note 2)	$C_{OSS(EQ)}$	$V_{GS}=0V, V_{DS}=0V\sim 400V$		34		pF
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	$t_{D(ON)}$	$V_{DS}=30V, I_D=0.5A, R_G=25\Omega$		56		ns
Turn-On Rise Time	t_R			78		ns
Turn-Off Delay Time	$t_{D(OFF)}$			140		ns
Turn-Off Fall Time	t_F			72		ns
Total Gate Charge	Q_G	$V_{DS}=50V, I_D=1.3A, V_{GS}=10V$		25.9		nC
Gate-Source Charge	Q_{GS}			7		nC
Gate-Drain Charge	Q_{GD}			7.6		nC
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Diode Forward Voltage(Note 1)	V_{SD}	$I_{SD}=3A, V_{GS}=0V$			1.6	V
Source-Drain Current	I_{SD}				3	A
Source-Drain Current (Pulsed)	I_{SDM}				12	A

Notes: 1. Pulse width=300 μ s, Duty cycle \leq 1.5%

2. $C_{OSS(EQ)}$ is defined as a constant equivalent capacitance giving the same charging time as C_{OSS} when V_{DS} increases from 0 to 80% V_{DSS} .

■ TEST CIRCUITS AND WAVEFORMS

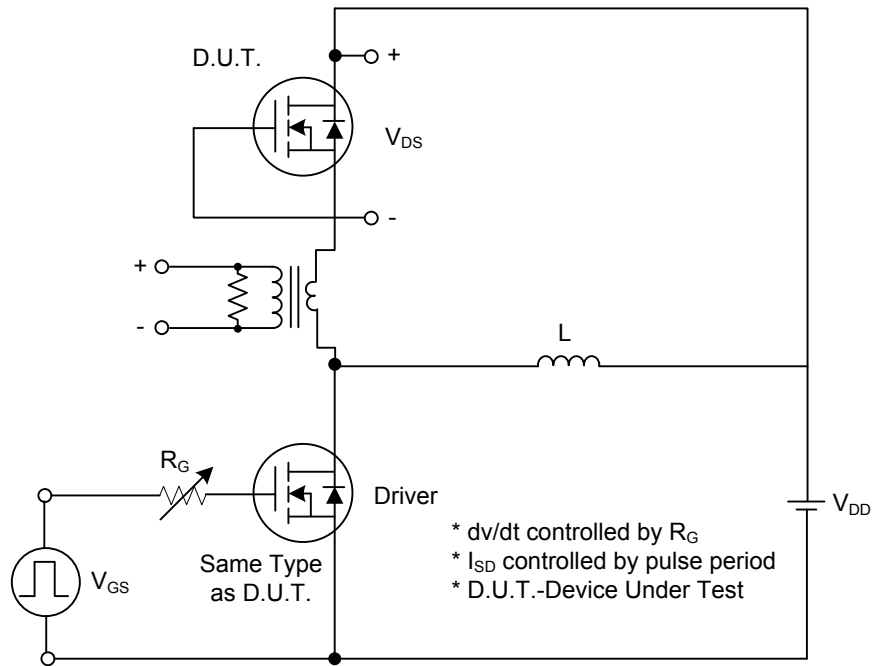


Fig. 1A Peak Diode Recovery dv/dt Test Circuit

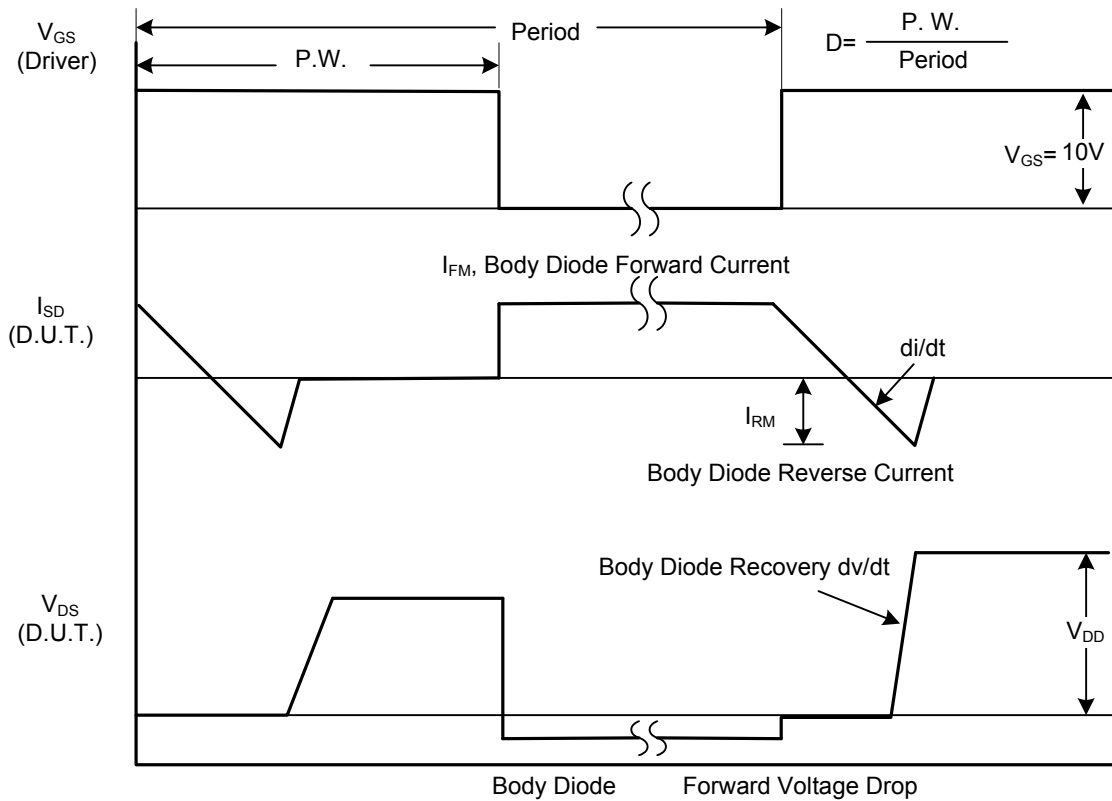


Fig. 1B Peak Diode Recovery dv/dt Waveforms

■ TEST CIRCUITS AND WAVEFORMS (Cont.)

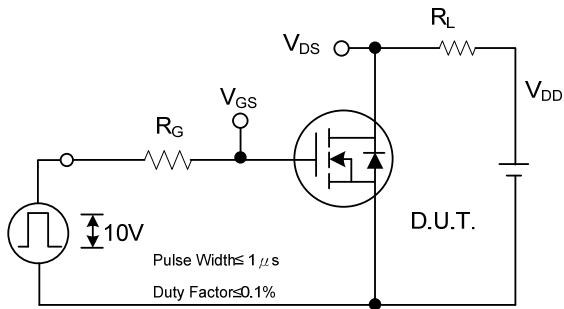


Fig. 2A Switching Test Circuit

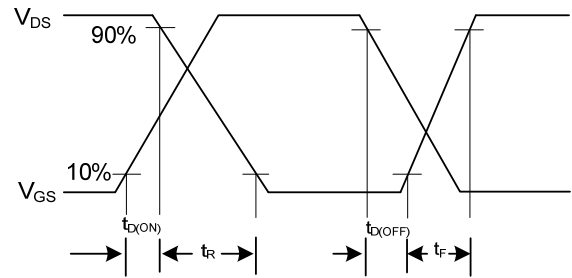


Fig. 2B Switching Waveforms

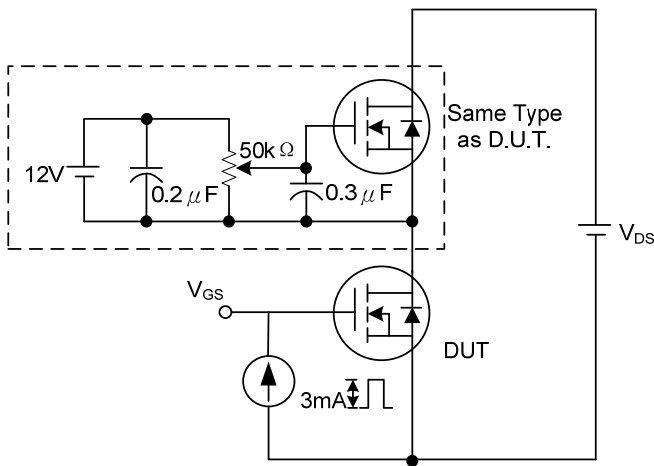


Fig. 3A Gate Charge Test Circuit

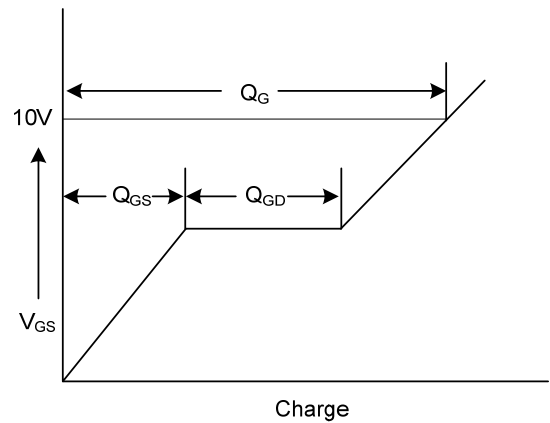


Fig. 3B Gate Charge Waveform

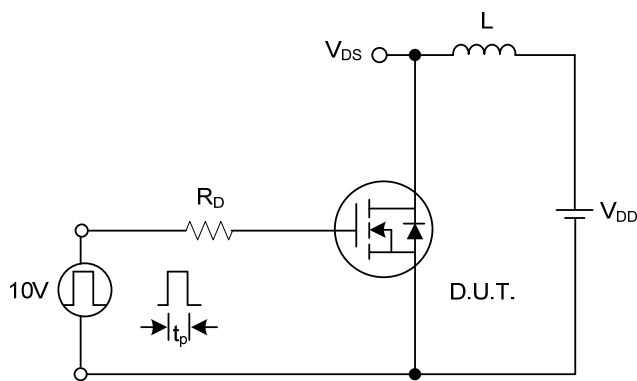


Fig. 4A Unclamped Inductive Switching Test Circuit

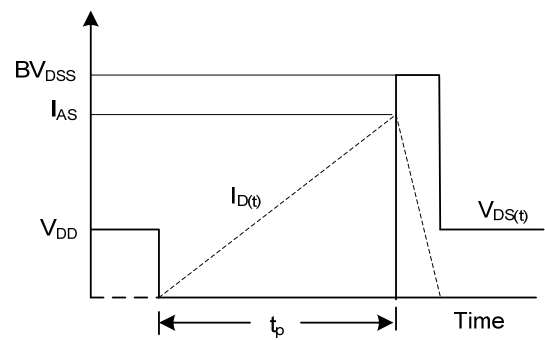
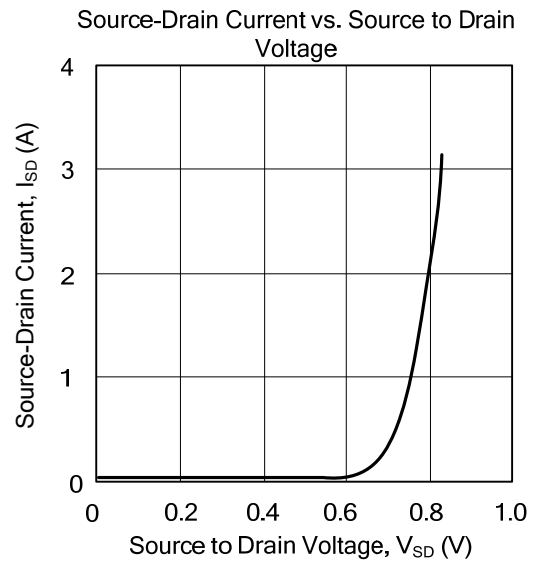
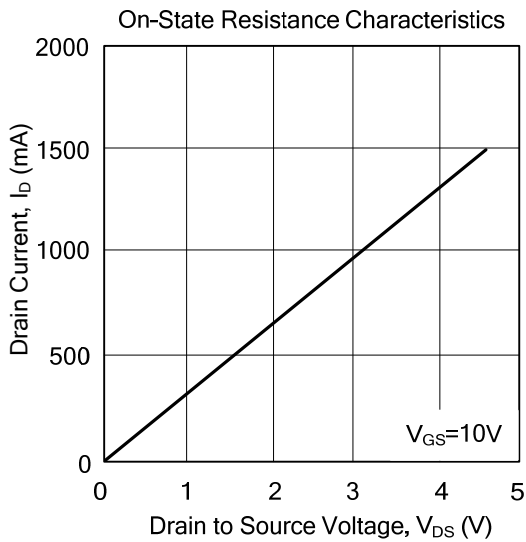
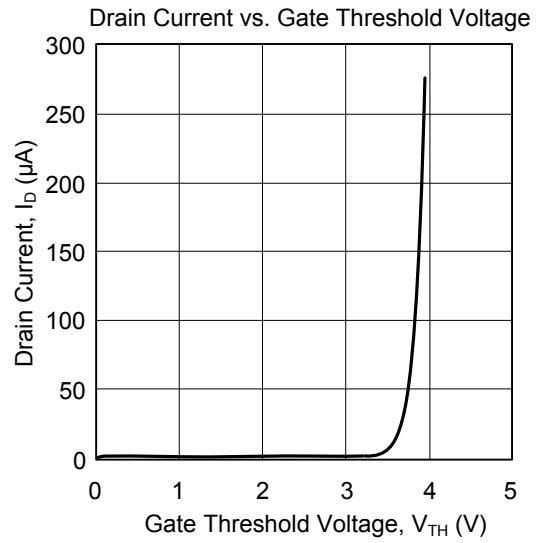
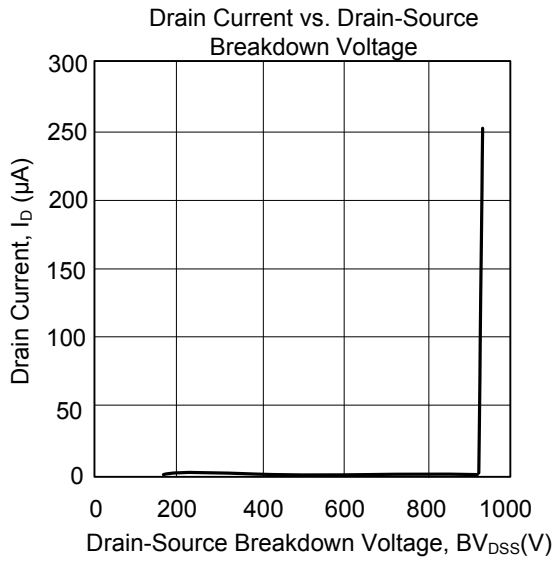


Fig. 4B Unclamped Inductive Switching Waveforms

TYPICAL CHARACTERISTICS



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